

# NSR0340P2

## 40 V Schottky Barrier Diode

Schottky barrier diodes are optimized for very low forward voltage drop and low leakage current and are used in a wide range of dc–dc converter, clamping and protection applications in portable devices. NSR0340P2 in a SOD–923 miniature package enables designers to meet the challenging task of achieving higher efficiency and meeting reduced space requirements.

### Features

- Very Low Forward Voltage Drop – 420 mV @ 100 mA
- Low Reverse Current – 0.6  $\mu$ A @ 10 V
- Continuous Forward Current – 200 mA
- Power Dissipation with Minimum Trace – 190 mW
- Very High Switching Speed – 3.0 ns @ 10 mA
- Low Capacitance – 4 pF @ 5.0 V
- This is a Pb–Free Device

### Typical Applications

- LCD and Keypad Backlighting
- Camera Photo Flash
- Buck and Boost dc–dc Converters
- Reverse Voltage and Current Protection
- Clamping & Protection

### Markets

- Mobile Handsets
- MP3 Players
- Digital Camera and Camcorders
- Notebook PCs & PDAs
- GPS

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Reverse Voltage	$V_R$	40	V
Forward Current (DC)	$I_F$	200	mA
Non–Repetitive Peak Forward Surge Current	$I_{FSM}$	1.0	A
ESD Rating: Human Body Model Machine Model	ESD	Class 2 Class A	

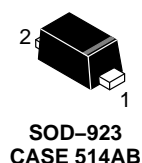
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



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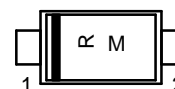
[www.onsemi.com](http://www.onsemi.com)

## 40 V SCHOTTKY BARRIER DIODE



SOD–923  
CASE 514AB

### MARKING DIAGRAM



R = Specific Device Code

M = Month Code

### ORDERING INFORMATION

Device	Package	Shipping†
NSR0340P2T5G	SOD–923 (Pb–Free)	2 mm Pitch 8000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

**THERMAL CHARACTERISTICS**

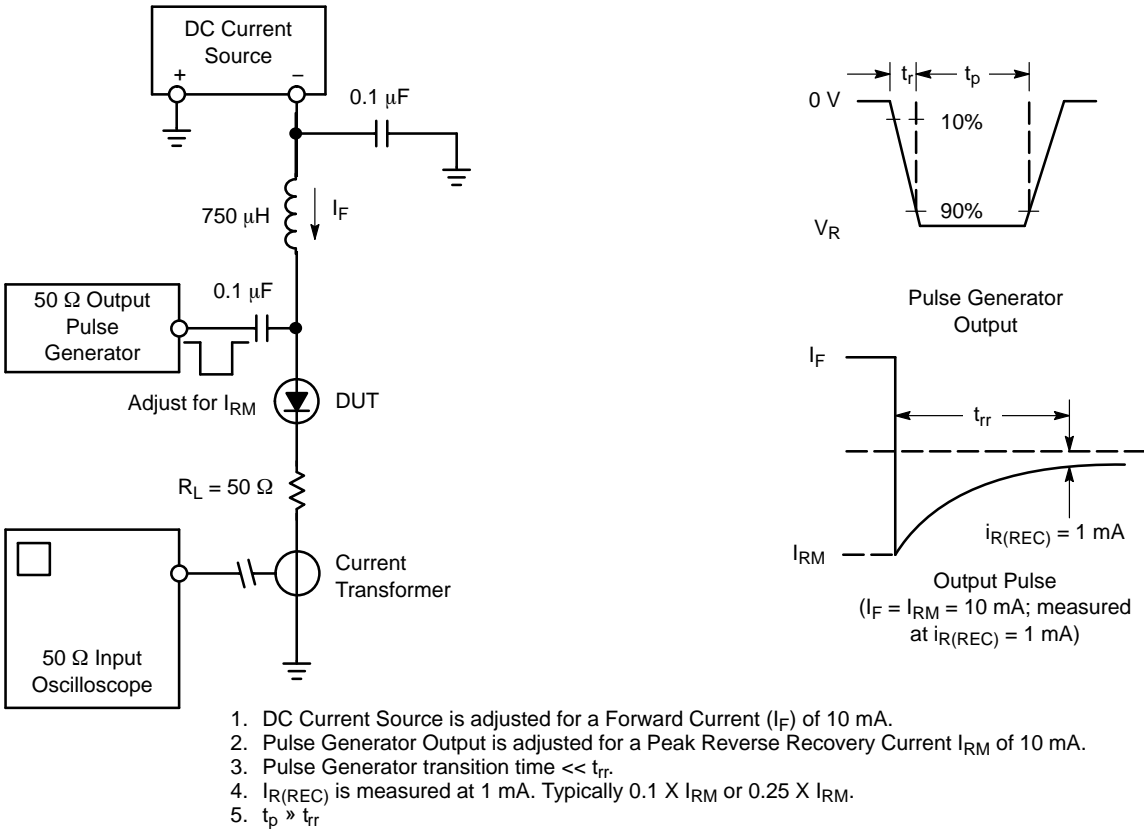
Characteristic	Symbol	Max	Unit
Thermal Resistance Junction-to-Ambient (Note 1) Total Power Dissipation @ $T_A = 25^\circ\text{C}$	$R_{\theta JA}$ $P_D$	520 190	$^\circ\text{C/W}$ mW
Thermal Resistance Junction-to-Ambient (Note 2) Total Power Dissipation @ $T_A = 25^\circ\text{C}$	$R_{\theta JA}$ $P_D$	175 570	$^\circ\text{C/W}$ mW
Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to +125	$^\circ\text{C}$

1. Mounted onto a 4 in square FR-4 board 10 mm sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.
2. Mounted onto a 4 in square FR-4 board 1 in sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.

**ELECTRICAL CHARACTERISTICS** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
Reverse Leakage ( $V_R = 10\text{ V}$ ) ( $V_R = 40\text{ V}$ )	$I_R$		0.6 4.0	5.0 20	$\mu\text{A}$
Forward Voltage ( $I_F = 10\text{ mA}$ ) ( $I_F = 100\text{ mA}$ ) ( $I_F = 200\text{ mA}$ )	$V_F$		290 420 520	320 460 560	mV
Total Capacitance ( $V_R = 5.0\text{ V}, f = 1\text{ MHz}$ )	CT		4.0		pF
Reverse Recovery Time ( $I_F = I_R = 10\text{ mA}, I_R = 1.0\text{ mA}$ )	$t_{rr}$		3.0		ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.



**Figure 1. Recovery Time Equivalent Test Circuit**

# NSR0340P2

## TYPICAL CHARACTERISTICS

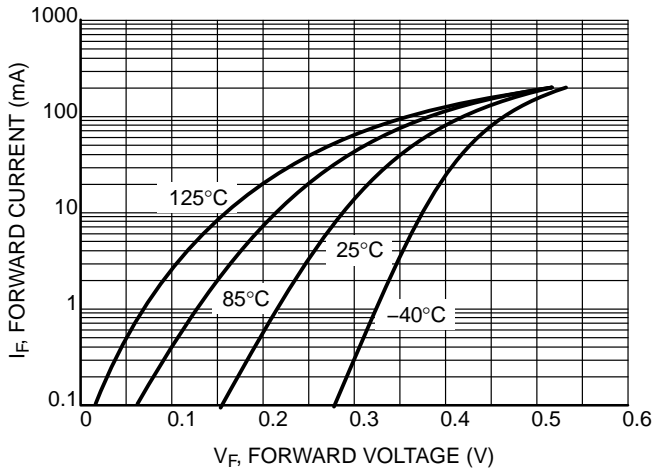


Figure 2.

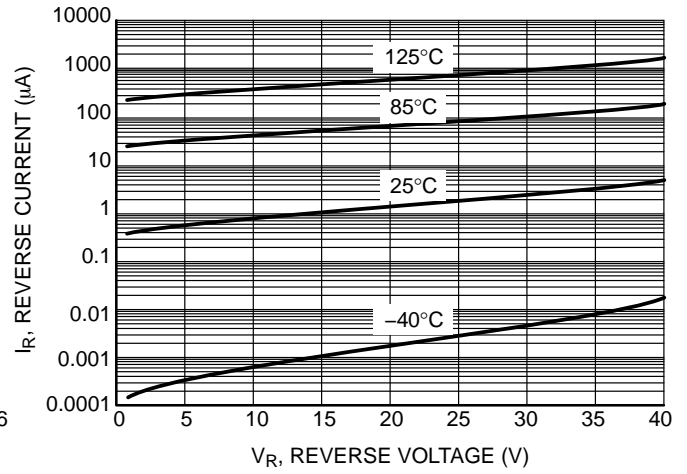


Figure 3.

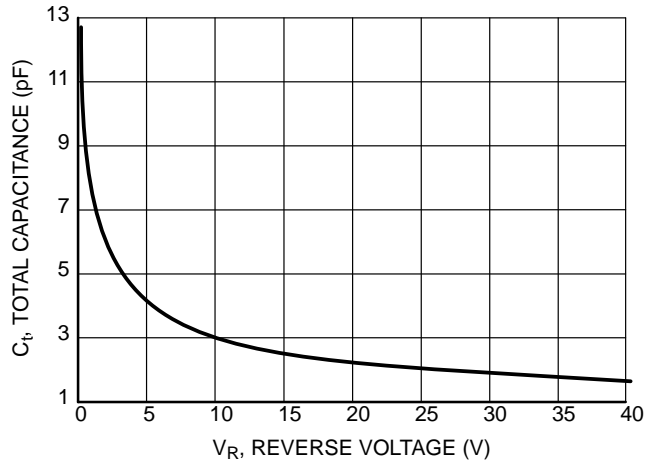
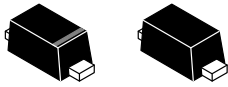


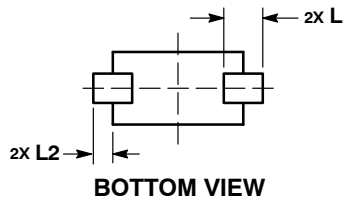
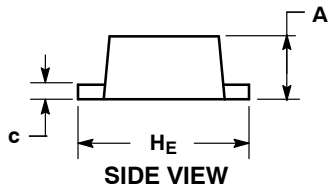
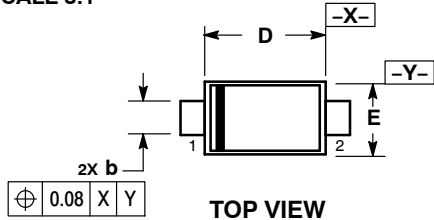
Figure 4.

# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

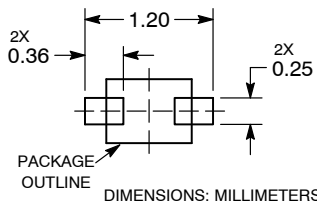


STYLE 1    STYLE 2

SCALE 8:1



### SOLDERING FOOTPRINT\*



**SOD-923  
CASE 514AB  
ISSUE D**

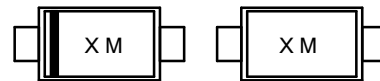
DATE 03 SEP 2020

#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
5. DIMENSION L WILL NOT EXCEED 0.30mm.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.34	0.37	0.40	0.013	0.015	0.016
b	0.15	0.20	0.25	0.006	0.008	0.010
c	0.07	0.12	0.17	0.003	0.005	0.007
D	0.75	0.80	0.85	0.030	0.031	0.033
E	0.55	0.60	0.65	0.022	0.024	0.026
HE	0.95	1.00	1.05	0.037	0.039	0.041
L	0.19 REF			0.007 REF		
L2	0.05	0.10	0.15	0.002	0.004	0.006

### GENERIC MARKING DIAGRAM\*



STYLE 1

STYLE 2

X = Specific Device Code  
M = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1:  
PIN 1. CATHODE (POLARITY BAND)  
2. ANODE

STYLE 2:  
NO POLARITY

See Application Note AND8455/D for more mounting details

\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>SOD-923, 1.0x0.6x0.37, MAX HEIGHT 0.40</b>	<b>PAGE 1 OF 1</b>

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